1410326-3 - ACTIVE

MULTIGIG RT | MULTIGIG RT 2

TE Internal #: 1410326-3 High Speed Backplane Connectors, 112 Position, Mating Alignment, Guide Slot Mating Alignment Type, 7 Row, 16 Column, PCB Mount Header, MULTIGIG RT 2

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Connectors > PCB Connectors > Backplane Connectors > High Speed Backplane Connectors



Connector System: Board-to-Board Number of Positions: 112 Row-to-Row Spacing: 1.35 mm [.053 in] Mating Alignment: With Mating Alignment Type: Guide Slot

Features

Product Type Features

Backplane Module Type	Center
Applied to Printed Circuit Board Type	Daughtercard
Connector System	Board-to-Board
PCB Connector Assembly Type	PCB Mount Header
Shroud Style	Fully Shrouded
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Ground Positions	31
Card Slot Centerline	20.3 mm[.8 in]
Number of Pairs	20
Backplane Architecture	Traditional Backplane
Number of Positions	112
Number of Rows	7
Number of Columns	16
PCB Mount Orientation	Right Angle
Guide Location	Right
Electrical Characteristics	

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09/26/2023 11:23AM | Page 1

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Impedance	100 Ω
Operating Voltage	50 VAC
Signal Characteristics	
Differential Impedance	100 Ω
Number of Differential Pairs per Column	2
Data Rate	≤12 Gb/s
Body Features	
Primary Product Color	Black
Contact Features	
Contact Mating Area Length	2.9 mm[.8 in]
PCB Contact Termination Area Plating Material Thickness	1.27 μm[50 μin]
Contact Layout	Inline
Contact Type	Pin
Contact Underplating Material Thickness	1.27 μm[50 μin]
Contact Mating Area Plating Material Thickness	1.27 μm[50 μin]
Contact Mating Area Plating Material	Gold
PCB Contact Termination Area Plating Material Finish	Bright
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Base Material	Copper
Contact Current Rating (Max)	1 A
Termination Features	
Termination Post & Tail Length	1.4 mm[.055 in]
Termination Method to Printed Circuit Board	Through Hole - Press-Fit
Mechanical Attachment	
Guide Hardware	With
Mating Retention	With
PCB Mount Alignment	With
PCB Mount Retention	With
PCB Mount Retention Type	Action/Compliant Tail
Mating Alignment	With
Mating Alignment Type	Guide Slot

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Connector Mounting Type	Board Mount
Housing Features	
Number of Shrouded Sides	2
Housing Material	LCP (Liquid Crystal Polymer)
Centerline (Pitch)	1.8 mm[.07 in]
Dimensions	
Connector Length	28.68 mm[1.129 in]
Connector Height	18.4 mm[.724 in]
PCB Thickness (Recommended)	1.6 – 4 mm[.062 – .157 in]
PCB Hole Diameter	.46 mm[.018 in]
Row-to-Row Spacing	1.35 mm[.053 in]
Usage Conditions	
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Operation/Application	
Durability Rating	500 Cycles
Circuit Application	Power & Signal
Packaging Features	

Tube

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Not Compliant
EU ELV Directive 2000/53/EC	Compliant with Exemptions
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2021 (211) SVHC > Threshold: Pb (7% in contact plating) Aticle Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.
Halogen Content	BFR/CFR/PVC Free, but Br/Cl >900 ppm in other sources.
Solder Process Capability	Not applicable for solder process capability

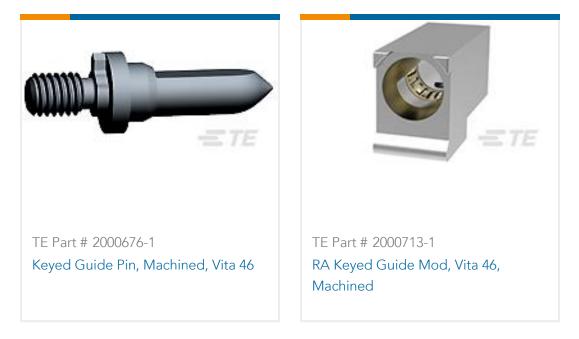
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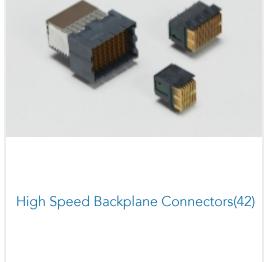
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series | MULTIGIG RT 2



Customers Also Bought



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Documents

Product Drawings MULTIGIG RT T2 7RW DC DF CT

English

CAD Files 3D PDF

3D

Customer View Model ENG_CVM_CVM_1410326-3_B.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_1410326-3_B.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1410326-3_B.3d_stp.zip

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Datasheets & Catalog Pages SOSA Aligned Interconnect Solutions

English

Board-Level Interconnects for Rugged Embedded Computing Brochure

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